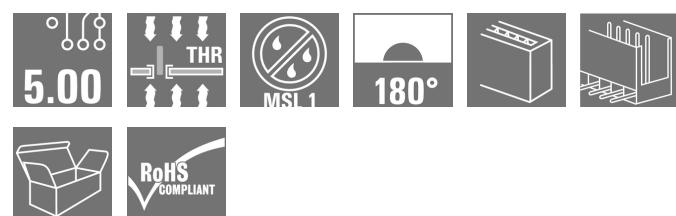


**SL-SMT 5.00HC/10/180 3.2SN BK BX**

**Weidmüller Interface GmbH & Co. KG**  
 Klingenbergsstraße 26  
 D-32758 Detmold  
 Germany

[www.weidmueller.com](http://www.weidmueller.com)

**Product image**

High-temperature-resistant, straight, open pin header.  
 Packed in box or tape. On tape and with 1.5 mm solder pin, optimised for automatic assembly. 3.2 mm solder pin suitable for reflow and wave soldering. The pin headers provide space for labelling and can be coded. HC = High Current.

**General ordering data**

Version	PCB plug-in connector, male header, open side, THT/THR solder connection, 5.00 mm, Number of poles: 10, 180°, Solder pin length (l): 3.2 mm, tinned, black, Box
Order No.	<a href="#">1841000000</a>
Type	SL-SMT 5.00HC/10/180 3.2SN BK BX
GTIN (EAN)	4032248351893
Qty.	50 pc(s).
Product data	IEC: 400 V / 27.5 A UL: 300 V / 18.5 A
Packaging	Box

Creation date September 16, 2022 7:05:05 PM CEST

**SL-SMT 5.00HC/10/180 3.2SN BK BX**

**Weidmüller Interface GmbH & Co. KG**  
 Klingenbergsstraße 26  
 D-32758 Detmold  
 Germany

[www.weidmueller.com](http://www.weidmueller.com)

**Technical data****Dimensions and weights**

Depth	8.5 mm	Depth (inches)	0.335 inch
Height	15.2 mm	Height (inches)	0.598 inch
Height of lowest version	12 mm	Width	50 mm
Width (inches)	1.969 inch	Net weight	4.16 g

**System specifications**

Product family	OMNIMATE Signal - series BL/SL 5.00	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	5 mm
Pitch in inches (P)	0.197 inch	Outgoing elbow	180°
Number of poles	10	Number of solder pins per pole	1
Solder pin length (l)	3.2 mm	Solder pin length tolerance	+0.1 / -0.2 mm
Solder pin dimensions	d = 1.2 mm, Octagonal	Solder pin dimensions = d tolerance	0 / -0.03 mm
Solder eyelet hole diameter (D)	1.5 mm	Solder eyelet hole diameter tolerance (D)+ 0.1 mm	
L1 in mm	45 mm	L1 in inches	1.772 inch
Number of rows	1	Pin series quantity	1
Protection degree	IP20	Volume resistance	≤5 mΩ
Can be coded	Yes	Plugging force/pole, max.	7 N
Pulling force/pole, max.	5.5 N		

**Material data**

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIIa
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	CuMg
Contact surface	tinned	Layer structure of solder connection	1...3 µm Ni / 2...4 µm Sn matt
Layer structure of plug contact	1...3 µm Ni / 2...4 µm Sn matt	Storage temperature, min.	-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	100 °C	Temperature range, installation, min.	-30 °C
Temperature range, installation, max.	100 °C		

**Rated data acc. to IEC**

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	27.5 A
Rated current, max. number of poles (Tu=20°C)	19 A	Rated current, min. number of poles (Tu=40°C)	24 A
Rated current, max. number of poles (Tu=40°C)	16.5 A	Rated voltage for surge voltage class / pollution degree II/2	400 V
Rated voltage for surge voltage class / pollution degree III/2	320 V	Rated voltage for surge voltage class / pollution degree III/3	250 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	4 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	4 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	4 kV		

**SL-SMT 5.00HC/10/180 3.2SN BK BX**

**Weidmüller Interface GmbH & Co. KG**  
 Klingenbergsstraße 26  
 D-32758 Detmold  
 Germany

[www.weidmueller.com](http://www.weidmueller.com)

**Technical data****Rated data acc. to CSA**

Institute (CSA)



Certificate No. (CSA)

200039-1176845

Rated voltage (Use group B / CSA) 300 V

Rated voltage (Use group D / CSA) 300 V

Rated current (Use group B / CSA) 15 A

Rated current (Use group D / CSA) 15 A

Reference to approval values  
 Specifications are  
 maximum values, details -  
 see approval certificate.

**Packing**

Packaging

Box

VPE length

153 mm

VPE width

112 mm

VPE height

33 mm

**Classifications**

ETIM 6.0

EC002637

ETIM 7.0

EC002637

ETIM 8.0

EC002637

ECLASS 9.0

27-44-04-02

ECLASS 9.1

27-44-04-02

ECLASS 10.0

27-44-04-02

ECLASS 11.0

27-46-02-01

ECLASS 12.0

27-46-02-01

**Important note**

IPC conformity

Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.

Notes

- Gold-plated contact surfaces on request
- Rated current related to rated cross-section & min. No. of poles.
- Diameter of solder eyelet D = 1.4+0.1mm
- Solder eyelet diameter D = 1.5 + 0.1 mm, from 9 poles
- P on drawing = pitch
- Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards.
- Long term storage of the product with average temperature of 50 °C and average humidity 70%, 36 months

**Approvals**

Approvals



ROHS

Conform

UL File Number Search

UL Website

Certificate No. (UR)

E60693

**SL-SMT 5.00HC/10/180 3.2SN BK BX**

**Weidmüller Interface GmbH & Co. KG**  
Klingenbergsstraße 26  
D-32758 Detmold  
Germany

[www.weidmueller.com](http://www.weidmueller.com)

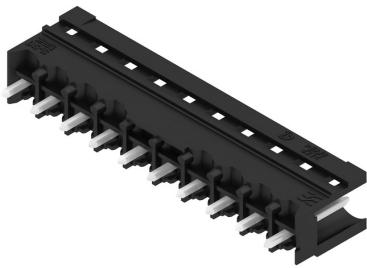
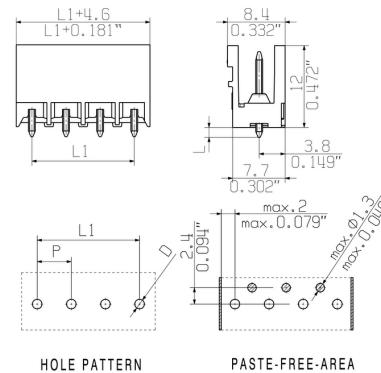
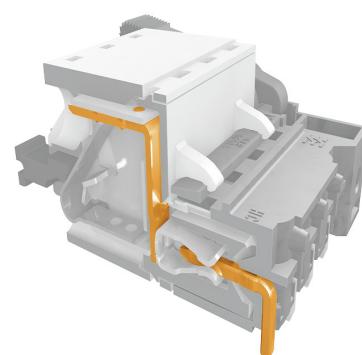
**Technical data****Downloads**

Approval/Certificate/Document of Conformity	<a href="#">Declaration of the Manufacturer</a>
Engineering Data	<a href="#">CAD data – STEP</a>
Catalogues	<a href="#">Catalogues in PDF-format</a>
Brochures	<a href="#">FL DRIVES EN</a> <a href="#">MB SMT EN</a> <a href="#">FL DRIVES DE</a> <a href="#">MB DEVICE MANUF. EN</a> <a href="#">FL BUILDING SAFETY EN</a> <a href="#">FL APPL LED LIGHTING EN</a> <a href="#">FL INDUSTR.CONTROLS EN</a> <a href="#">FL MACHINE SAFETY EN</a> <a href="#">FL HEATING ELECTR EN</a> <a href="#">FL_APPL_INVERTER EN</a> <a href="#">FL_BASE_STATION EN</a> <a href="#">FL_ELEVATOR EN</a> <a href="#">FL_POWER_SUPPLY EN</a> <a href="#">FL_72H_SAMPLE_SER EN</a> <a href="#">PO_OMNIMATE EN</a> <a href="#">PO_OMNIMATE EN</a>
White paper surface mount technology	<a href="#">Download Whitepaper</a>

**SL-SMT 5.00HC/10/180 3.2SN BK BX**

**Weidmüller Interface GmbH & Co. KG**  
Klingenbergsstraße 26  
D-32758 Detmold  
Germany

[www.weidmueller.com](http://www.weidmueller.com)

**Drawings****Product image****Dimensional drawing****Product benefits**

Safe power transmission  
Proven properties

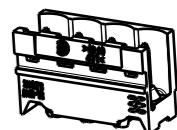
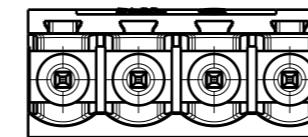
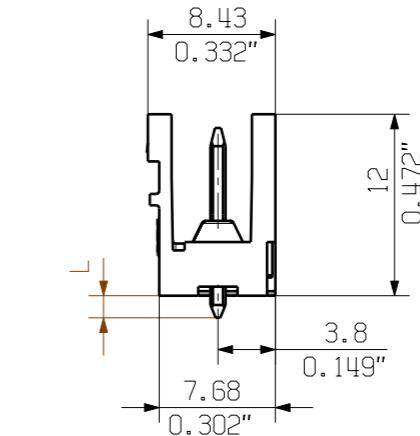
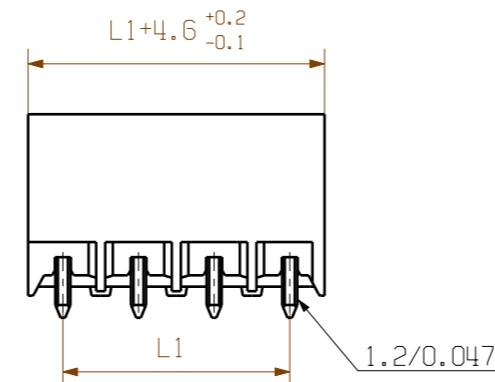
**SL-SMT 5.00HC/10/180 3.2SN BK BX**

**Weidmüller Interface GmbH & Co. KG**  
Klingenbergsstraße 26  
D-32758 Detmold  
Germany

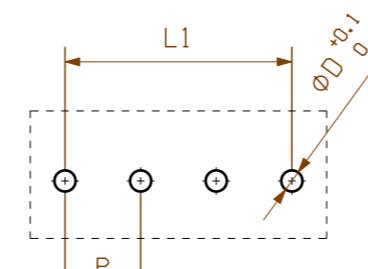
[www.weidmueller.com](http://www.weidmueller.com)

**Drawings****Product benefits**

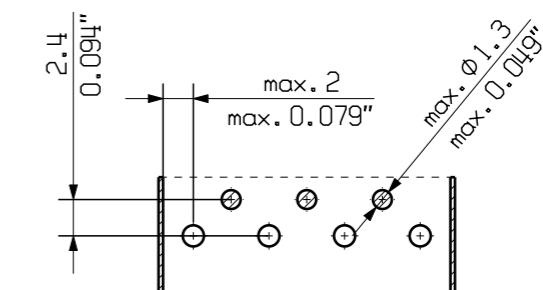
Compliant with existing standards



1/1



HOLE PATTERN



PASTE-FREE-AREA

D = 1.4/0.055" or 1.5/0.059" (REFLOW SOLDERING)  
RECOMMENDATION FOR AUTOMATIC ASSEMBLY  
(1.4mm FOR n=2...8 / 1.5mm for n=9...24)

P=RASTER/PITCH

SHOWN: SL-SMT 5.00HC/04/180

STIFTLAENGE L	TOLERANZ
1,5	0,0
	-0,3
3,2	0,1
	-0,3
<b>n L1 [mm] L1 [Inch]</b>	

24	115,00	4,528
23	110,00	4,331
22	105,00	4,134
21	100,00	3,937
20	95,00	3,740
19	90,00	3,543
18	85,00	3,346
17	80,00	3,150
16	75,00	2,953
15	70,00	2,756
14	65,00	2,559
13	60,00	2,362
12	55,00	2,165
11	50,00	1,969
10	45,00	1,772
9	40,00	1,575
8	35,00	1,378
7	30,00	1,181
6	25,00	0,984
5	20,00	0,787
4	15,00	0,591
3	10,00	0,394
2	5,00	0,197
n	L1 [mm] L1 [Inch]	

For the mounting of PCBs, it should be noted that the rated data stated here relates only to the PCB components alone.

The necessary creepage and clearance paths must be observed in connection with the respective applicant in accordance to IEC 664 / VDE 0110.

The current-carrying capacity and pitch tolerance is to be determined according to DIN IEC 326 part 3 very fine.

Weidmüller PCB components are tested to the DIN EN 61984 standard, and are valid for its field of application. Provided that the components are used to the intended purpose, all requirements with respect to the occurring of electrical, mechanical, thermic and corrosive stress will be satisfied.

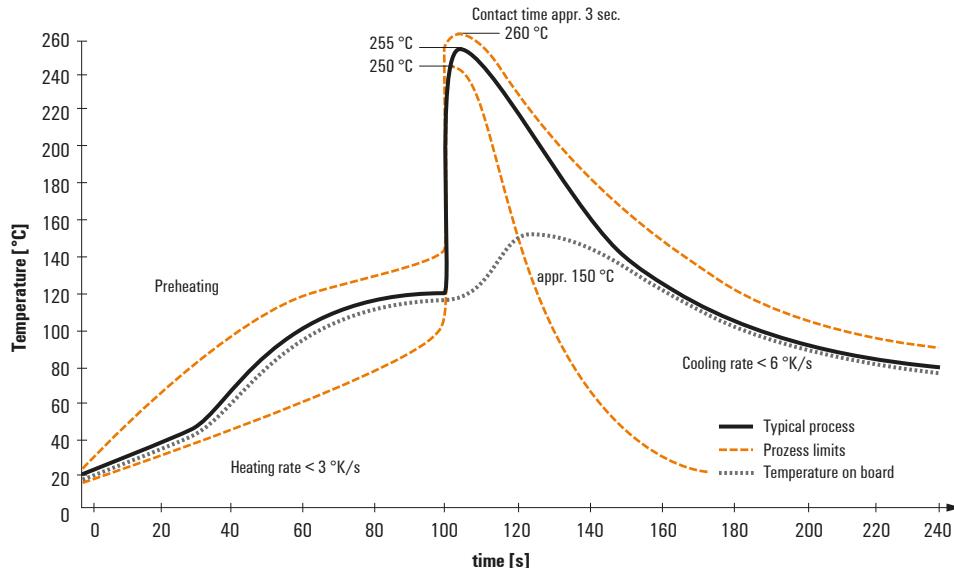
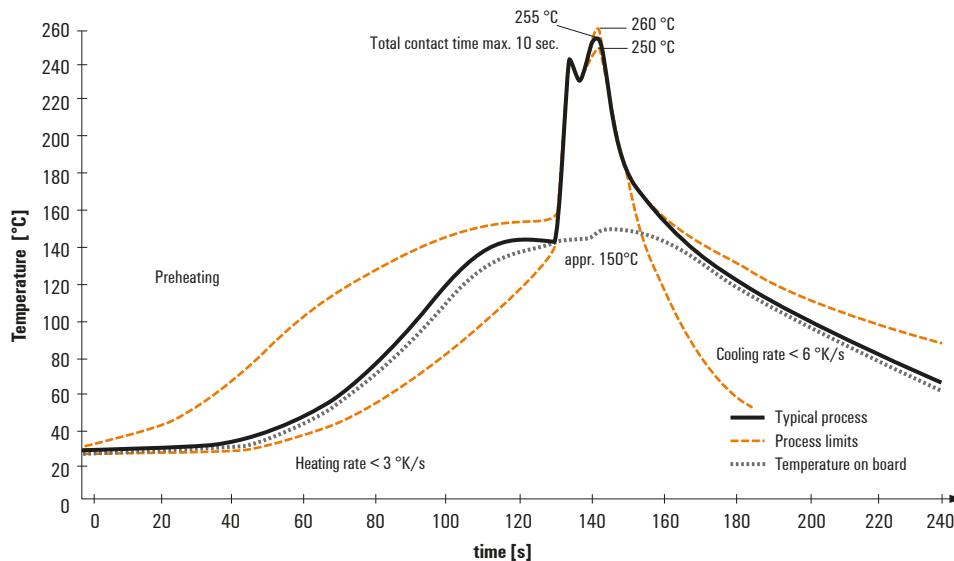
 DIN ISO 2768-m	106340/4 30.07.18 HERTEL_S 00		Modification	Weidmüller		C 34165 07	
	Date	Name				Cat. no.:	
	Drawn	22.01.2008 HERTEL_S					
	Responsible						
Scale: 2/1	Checked	27.08.2018 HERTEL_S					
Supersedes: .	Approved		LANG_T	Product file: SL-SMT 5.00			
				7279			

Drawing no. 01 of 04 sheets

SL-SMT 5.00HC/..180...  
STIFTLEISTE  
PIN HEADER

## Recommended wave soldering profiles

**Weidmüller Interface GmbH & Co. KG**  
 Klingenbergsstraße 16  
 D-32758 Detmold  
 Germany  
 Fon: +49 5231 14-0  
 Fax: +49 5231 14-292083  
[www.weidmueller.com](http://www.weidmueller.com)

**Single Wave:****Double Wave:****Wave soldering profiles**

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

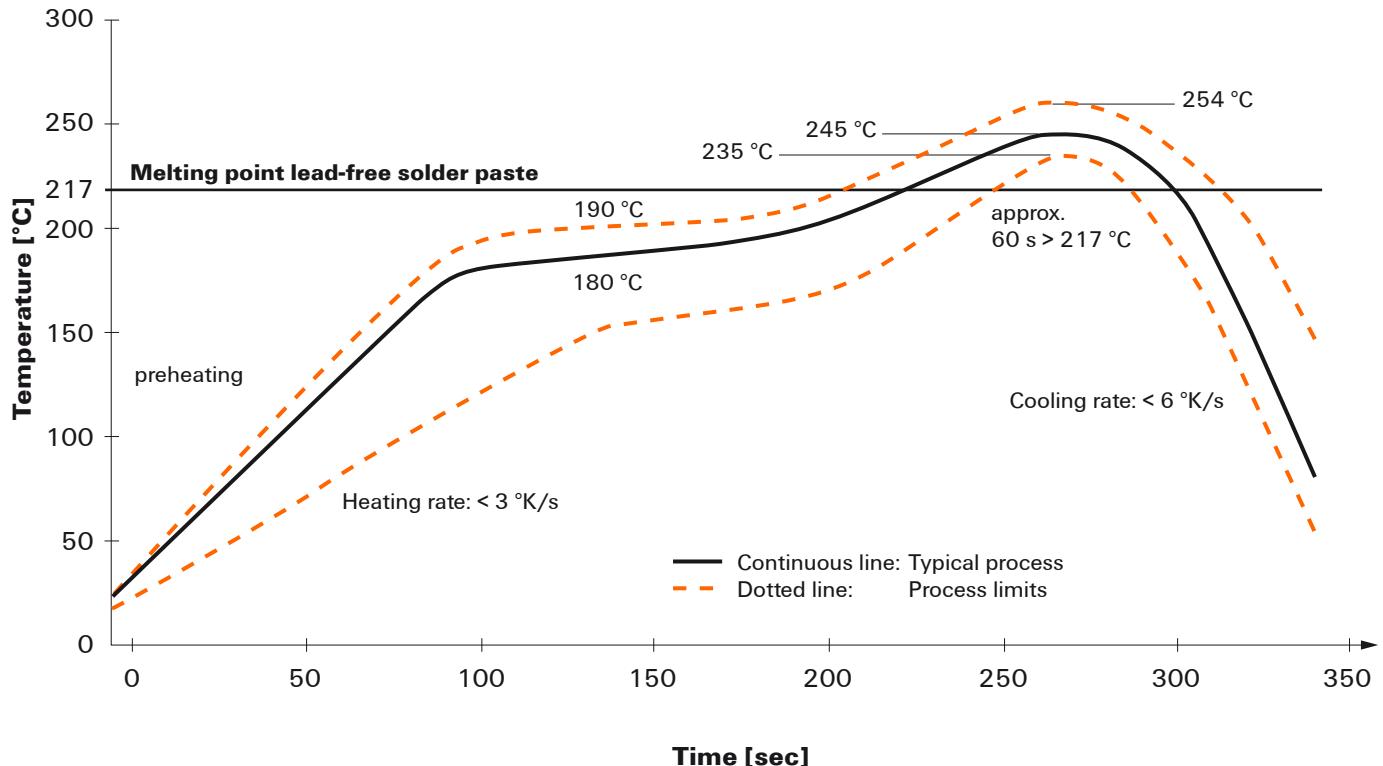
When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

## Recommended reflow soldering profile

Weidmüller Interface GmbH & Co. KG  
 Klingenbergsstraße 16  
 D-32758 Detmold  
 Germany  
 Fon: +49 5231 14-0  
 Fax: +49 5231 14-292083  
[www.weidmueller.com](http://www.weidmueller.com)



## Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically  $\leq +3\text{K/s}$ . In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at  $\geq -6\text{K/s}$  solder is cured. Board and components cool down while avoiding cold cracks.